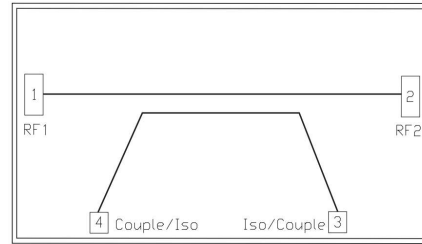


Performance

- Frequency: 1.2~1.4GHz
- Coupling: 19dB
- Directivity: ≥ 23 dB
- Chip size: 2.05*1.65*0.1mm

Function Diagram

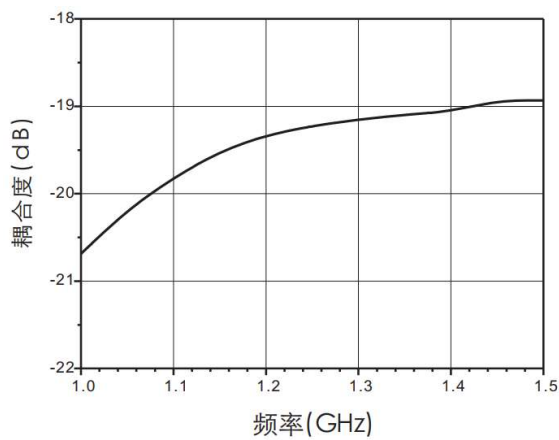


Electrical Specifications (Ta=+25°C, 50Ω system)

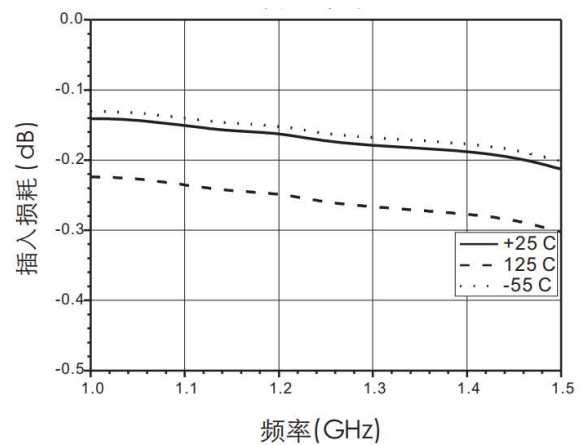
| Parameter | Min | Typical | Max | Unit |
|-----------------------------|---------|---------|------|------|
| Frequency Range | 1.2~1.4 | | | GHz |
| Coupling | 18.5 | 19 | 19.5 | |
| Insertion Loss | - | 0.2 | - | dB |
| Input Return loss | - | 20 | - | dB |
| Thru Output Return loss | - | 20 | - | dB |
| Coupling Output Return loss | - | 20 | - | dB |

Test Curves (Die chip + Bonding line test)

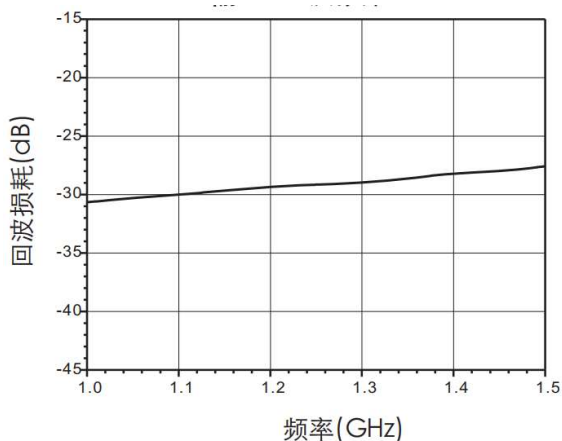
Coupling vs. Freq



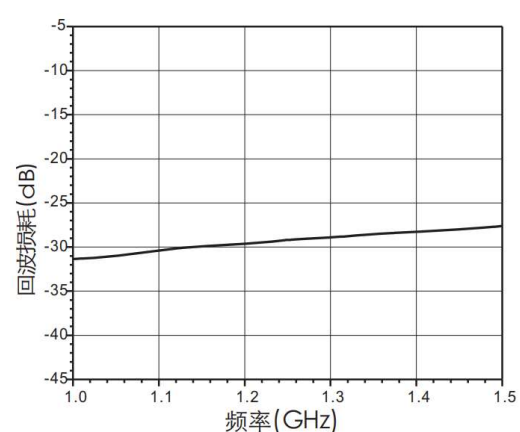
Insertion loss vs. Freq

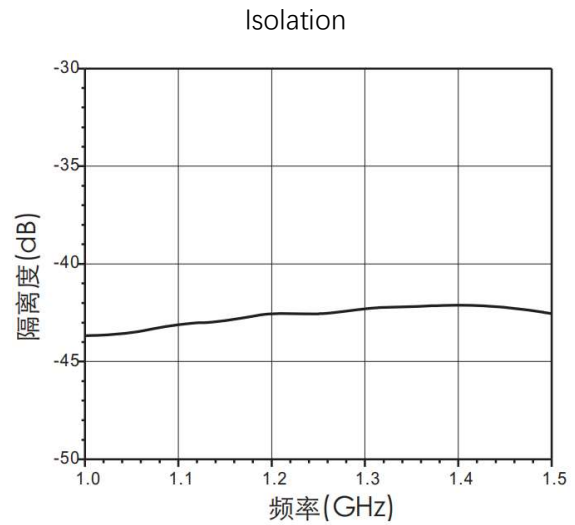
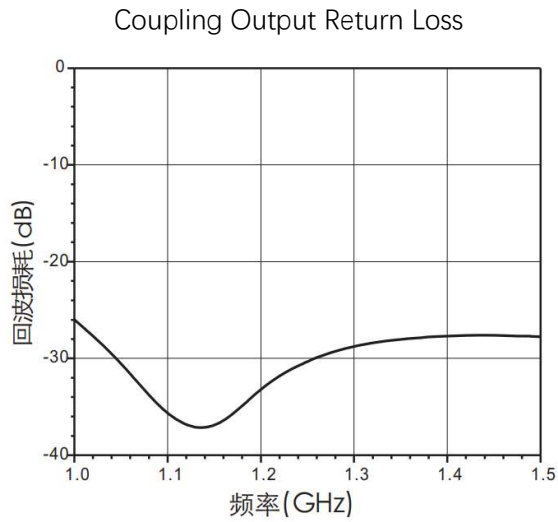


Input Return Loss vs. Freq

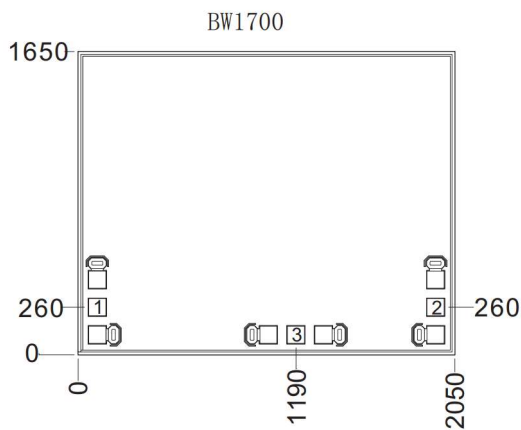


Thru output Return loss vs. Freq

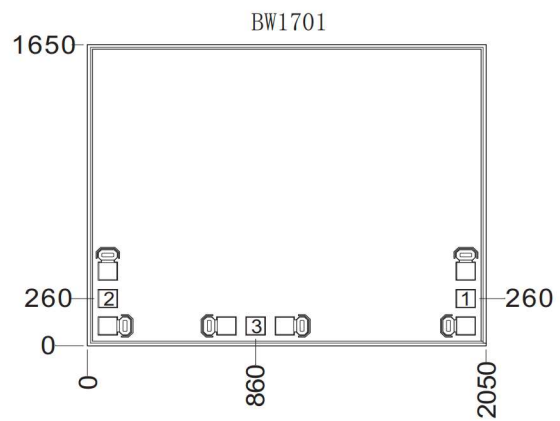




Outline Size



Note:



1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated,
Pad size: 100*100(um)
5. Don't bonding on thru holds
6. Tolerance: ±50um

Absolute Rating

| | |
|-------------------------|------------|
| Storage Temperature | -65~+150°C |
| Operating Temperature | -55~+125°C |
| Max Input Power | 50W |
| Static Protection (HBM) | Class 1A |



Bonding Pads Definition

| Number | Symbol | Description |
|--------|--------|------------------------|
| 1 | RFin | RF input port, 50ohm |
| 2 | RFout | RF output port, 50 ohm |
| 3 | Couple | Coupling ouput |

Application

